# **DSC612NI3A-010G**



## **Two-Output Low Power MEMS Clock Generator**

## **General Description**

The DSC612NI3A-010G is a two-output low power MEMS clock generator.

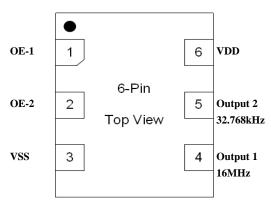
The MEMS based clock generator eliminates the need of external crystal or reference clock.

Refer to DSC612 master data sheet to read full descriptions.

#### **Features**

- Two LVCMOS clock outputs: 16MHz, 32.768kHz
- Ultra-small package size: 2.0mm x 1.6mm 6L LGA
- High stability: ±20ppm
- Temperature range: -40°C to +85°C
- Low power consumption: ~5mA (both outputs active)
- Wide supply voltage range: 1.71V -3.63V VDD
- Excellent shock and vibration immunity
- High reliability
- Lead free and RoHS compliant
- AEC-Q100 automotive grade available

# Pin Configuration and Description



6-pin 2.0mm x 1.6mm 6L LGA

Pin Number	Pin Name	Pin Type	Pin Description		
1	OE-1	I	Output Enable $H = \text{Output Active} \\ L = \text{Output Disabled (High Impedance)}$		
2	OE-2	I	Output Enable H = Output Active L = Output Disabled (High Impedance)		
3	VSS	Power	Power Supply Ground		
4	Output 1	О	16MHz LVCMOS Clock Output Controlled by Pin 1 (OE-1)		
5	Output 2	О	32.768kHz LVCMOS Clock Output Controlled by Pin 2 (OE-2)		
6	VDD	Power	Power Supply		

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## **Ordering Information**

Ordering Part Number	Temperature Range	High Stability	Shipping	Package
DSC612NI3A-010G	-40°C to +85°C	±20ppm	Bag	2.0mm x 1.6mm 6L LGA
DSC612NI3A-010GT	-40°C to +85°C	±20ppm	Tape and Reel	2.0mm x 1.6mm 6L LGA

Devices are Green and RoHS compliant. Sample material may have only a partial top mark.

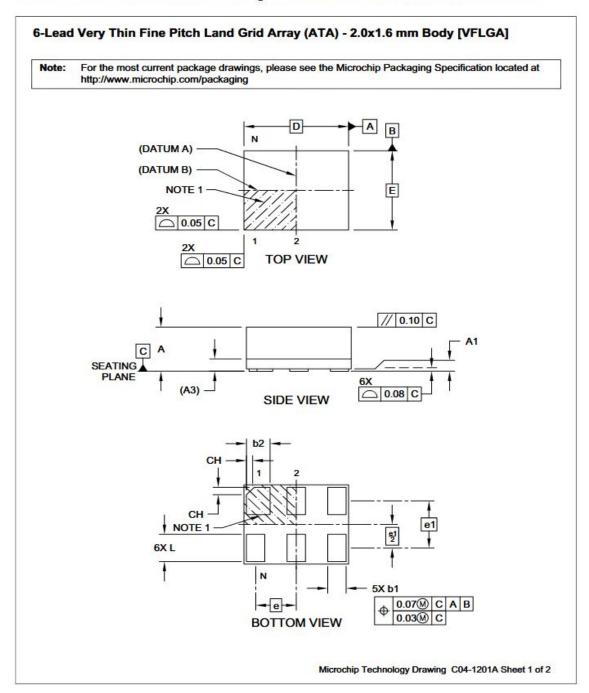
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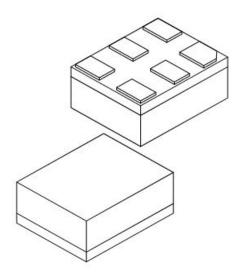
6-Lead 2.0 mm x 1.6 mm VFLGA Package Outline and Recommended Land Pattern

Microchip Technology Inc.



### 6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		MILLIMETERS		
Dimension	MIN	NOM	MAX	
Number of Terminals	N	6		
Terminal Pitch	е	0.775 BSC		
Terminal Pitch	e1	0.95 BSC		
Overall Height	Α	0.79	0.84	0.89
Standoff	A1	0.00	0.02	0.05
Substrate Thickness (with Terminals)	A3	0.20 REF		
Overall Length	D	2.00 BSC		
Overall Width	E	1.60 BSC		
Terminal Width	b1	0.30	0.35	0.40
Terminal Width	b2	0.40	0.45	0.50
Terminal Length	L	0.50	0.55	0.60
Terminal 1 Index Chamfer	CH	-	0.15	-

#### Notes:

- Pin 1 visual index feature may vary, but must be located within the hatched area.
   Package is saw singulated
- 3. Dimensioning and tolerancing per ASME Y14.5M

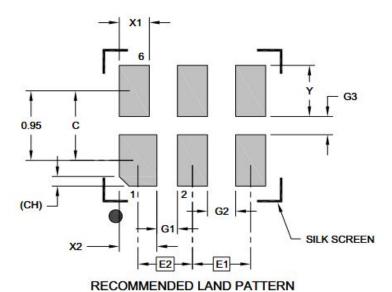
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.

Microchip Technology Drawing C04-1201A Sheet 2 of 2

### 6-Lead Very Thin Fine Pitch Land Grid Array (ATA) - 2.0x1.6 mm Body [VFLGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension	Dimension Limits		NOM	MAX
Contact Pitch	E1	0.78 BSC		
Contact Pitch	E2	0.73 BSC		
Contact Spacing	С		0.95	
Contact Width (X4)	X1			0.40
Contact Width (X2)	X2			0.45
Contact Pad Length (X6)	Y			0.70
Space Between Contacts (X4)	G1	0.28		
Space Between Contacts (X3)	G2	0.38		
Space Between Contacts (X3)	G3	0.25		
Contact 1 Index Chamfer	CH	0.13 X 45° REF		

#### Notes:

Dimensioning and tolerancing per ASME Y14.5M
 BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-3201A